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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



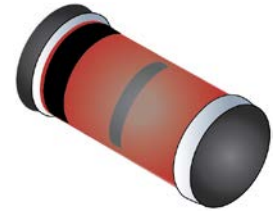


500 mW SURFACE MOUNT ZENER DIODES

Screening in reference to MIL-PRF-19500 available

DESCRIPTION

The 1N4678UR-1 thru 1N4717UR-1 series of 0.5 watt glass surface mount DO-213AA Zener voltage regulators provides a selection from 1.8 to 43 volts. Standard tolerance is +/-5%, with 1% and 2% options available. The Zener test current is only 50 uA. The metal slugs that sandwich the die are metallurgically bonded to the silicon for high reliability. This type of internally bonded Zener package construction is also available with high-reliability up-screening as described in the Features section. Microsemi also offers numerous other Zener products to meet higher and lower power applications.




DO-213AA Package

Important: For the latest information, visit our website <http://www.microsemi.com>.

FEATURES

- Surface mount equivalent of JEDEC registered 1N4678 thru 1N4717 series.
- Internal metallurgical bond.
- Hermetically sealed surface mount package.
- Tighter voltage tolerances of 2% and 1% are available.
- Up-screening available in reference to MIL-PRF-19500. (See [part nomenclature](#) for all available options.)
- RoHS compliant devices available (commercial grade only).

Also available in:

 **DO-35 (DO-204AH)**
(surface mount)
[1N4678-1 – 1N4717-1](#)

APPLICATIONS / BENEFITS

- Regulates voltage over a broad operating current and temperature range.
- Voltage selection from 1.8 to 43 V.
- Non-sensitive to ESD per MIL-STD-750 method 1020.
- Minimal capacitance (see [Figure 2](#)).
- Inherently radiation hard as described in Microsemi's "[MicroNote 050](#)".

MAXIMUM RATINGS

Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	T _J and T _{STG}	-65 to +175	°C
Thermal Resistance Junction-to-End Cap ⁽¹⁾	R _{θJL}	100	°C/W
Thermal Resistance Junction-to-Ambient ⁽¹⁾	R _{θJA}	250	°C/W
Steady-State Power Dissipation ⁽²⁾	P _D	0.5	W
Forward Voltage @ 100 mA	V _F	1.5	V
Solder Temperature @ 10 s	T _{SP}	260	°C

Notes: 1. When mounted on FR4 PC board (1 oz Cu) with recommended footprint (see last page).
2. At T_{EC} ≤ 125 °C or at ambient T_A ≤ 50 °C when mounted on FR4 PC board.

MSC – Lawrence
6 Lake Street,
Lawrence, MA 01841
Tel: 1-800-446-1158 or
(978) 620-2600
Fax: (978) 689-0803

MSC – Ireland
Gort Road Business Park,
Ennis, Co. Clare, Ireland
Tel: +353 (0) 65 6840044
Fax: +353 (0) 65 6822298

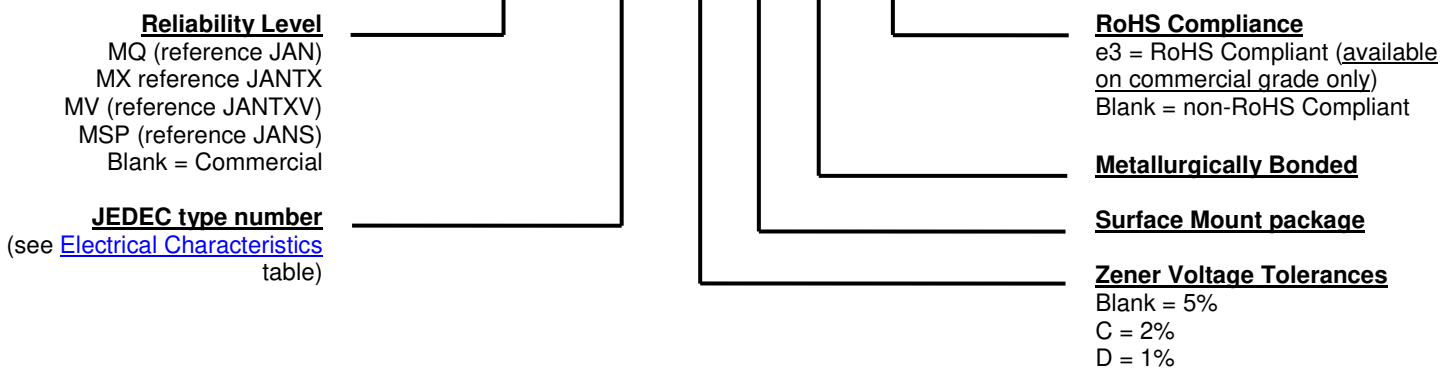
Website:
www.microsemi.com

MECHANICAL and PACKAGING

- CASE: Hermetically sealed glass DO-213AA (SOD80 or MLL34) MELF style package.
- TERMINALS: End caps available with tin-lead plating or RoHS compliant matte-tin plating (commercial version only). Solderable per MIL-STD-750, method 2026.
- POLARITY: Cathode indicated by band where diode is to be operated with the banded end positive with respect to the opposite end for Zener regulation.
- MARKING: The cathode is the banded end of the device.
- TAPE & REEL option: Standard per EIA-481-1-B (add "TR" suffix to part number). Consult factory for quantities.
- WEIGHT: 0.04 grams.
- See [Package Dimensions](#) on last page.

PART NOMENCLATURE

MQ 1N4678 C UR -1 (e3)


SYMBOLS & DEFINITIONS

Symbol	Definition
I_{ZT} or I_{ZK}	Regulator Current: The dc regulator current (I_Z), at a specified test point (I_{ZT}), near breakdown knee (I_{ZK}).
I_R	Reverse Current: The maximum reverse (leakage) current that will flow at the specified voltage and temperature.
I_{ZM}	Maximum Regulator (Zener) Current: The maximum rated dc current for the specified power rating.
T_{SP}	Temperature Solder Pad: The maximum solder temperature that can be safely applied to the terminal.
V_R	Reverse Voltage: The reverse voltage dc value, no alternating component.
V_Z	Zener Voltage: The Zener voltage the device will exhibit at a specified current (I_Z) in its breakdown region.

ELECTRICAL CHARACTERISTICS @ 25 °C unless otherwise noted.

JEDEC TYPE NUMBER (Note 1)	NOMINAL ZENER VOLTAGE (Note 3)	ZENER TEST CURRENT	MAXIMUM VOLTAGE REGULATION (Note 2 & 3)	MAXIMUM REVERSE LEAKAGE CURRENT		MAXIMUM dc ZENER CURRENT*
	V_Z	I_{ZT}	ΔV_Z	$I_R @ V_R$		I_{ZM}
	Volts	μA	Volts	μA	Volts	mA
1N4678UR-1	1.8	50	0.70	7.5	1.0	240
1N4679UR-1	2.0	50	0.70	5.0	1.0	220
1N4680UR-1	2.2	50	0.75	4.0	1.0	200
1N4681UR-1	2.4	50	0.80	2.0	1.0	190
1N4682UR-1	2.7	50	0.85	1.0	1.0	180
1N4683UR-1	3.0	50	0.90	0.8	1.0	170
1N4684UR-1	3.3	50	0.95	7.5	1.5	160
1N4685UR-1	3.6	50	0.95	7.5	2.0	150
1N4686UR-1	3.9	50	0.97	5.0	2.0	140
1N4687UR-1	4.3	50	0.99	4.0	2.0	130
1N4688UR-1	4.7	50	0.99	10.0	3.0	120
1N4689UR-1	5.1	50	0.97	10.0	3.0	110
1N4690UR-1	5.6	50	0.96	10.0	4.0	100
1N4691UR-1	6.2	50	0.95	10.0	5.0	90
1N4692UR-1	6.8	50	0.90	10.0	5.1	70
1N4693UR-1	7.5	50	0.75	10.0	5.7	63.6
1N4694UR-1	8.2	50	0.50	1.0	6.2	58.0
1N4695UR-1	8.7	50	0.10	1.0	6.6	54.8
1N4696UR-1	9.1	50	0.08	1.0	6.9	52.4
1N4697UR-1	10.0	50	0.10	1.0	7.6	49.6
1N4698UR-1	11.0	50	0.11	0.05	8.4	43.2
1N4699UR-1	12.0	50	0.12	0.05	9.1	40.8
1N4700UR-1	13.0	50	0.13	0.05	9.8	38.0
1N4701UR-1	14.0	50	0.14	0.05	10.6	35.0
1N4702UR-1	15.0	50	0.15	0.05	11.4	32.6
1N4703UR-1	16.0	50	0.16	0.05	12.1	30.8
1N4704UR-1	17.0	50	0.17	0.05	12.9	29.0
1N4705UR-1	18.0	50	0.18	0.05	13.6	26.4
1N4706UR-1	19.0	50	0.19	0.05	14.4	25.0
1N4707UR-1	20.0	50	0.20	0.01	15.2	23.8
1N4708UR-1	22.0	50	0.22	0.01	16.7	21.6
1N4709UR-1	24.0	50	0.24	0.01	18.2	19.8
1N4710UR-1	25.0	50	0.25	0.01	19.0	19.0
1N4711UR-1	27.0	50	0.27	0.01	20.4	17.6
1N4712UR-1	28.0	50	0.28	0.01	21.2	17.0
1N4713UR-1	30.0	50	0.30	0.01	22.8	15.8
1N4714UR-1	33.0	50	0.33	0.01	25.0	14.4
1N4715UR-1	36.0	50	0.36	0.01	27.3	13.2
1N4716UR-1	39.0	50	0.39	0.01	29.6	12.2
1N4717UR-1	43.0	50	0.43	0.01	32.6	11.0

*JEDEC registered data except that I_{ZM} has been increased (doubled) for 500 mW power dissipation capabilities.

- NOTES:**
1. All types as shown are +/-5% tolerance. Also available in 2% and 1% tolerance.
 2. $\Delta V_Z @ 100 \mu A$ minus $V_Z @ 10 \mu A$.
 3. The electrical characteristics are measured after allowing the device to stabilize for 20 seconds when mounted with 3/8" minimum lead length from the base.

GRAPHS

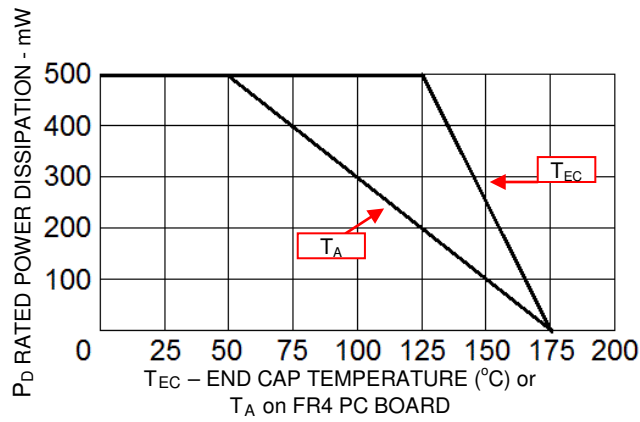


FIGURE 1
POWER DERATING CURVE

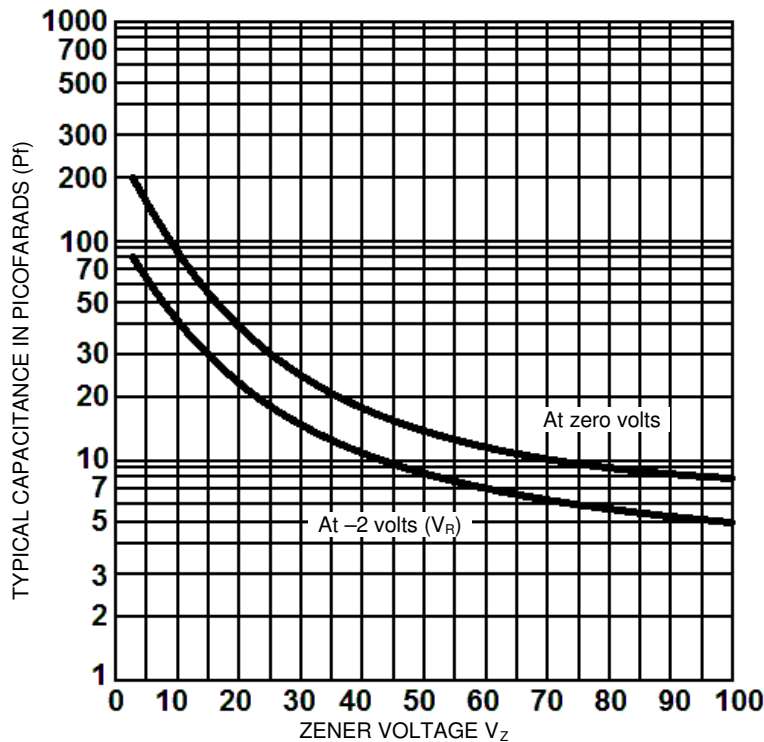
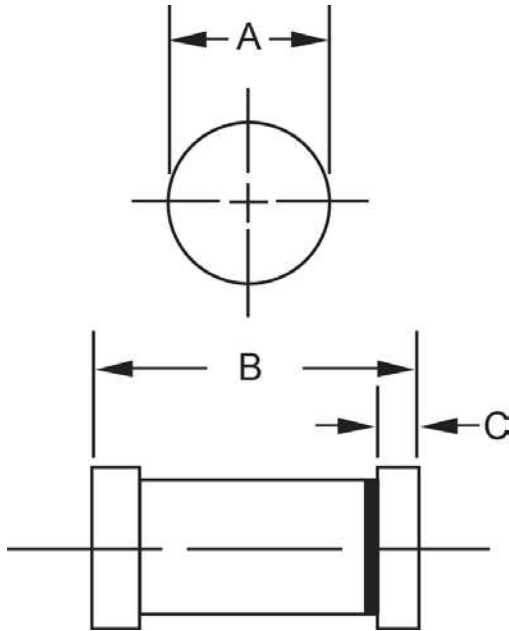
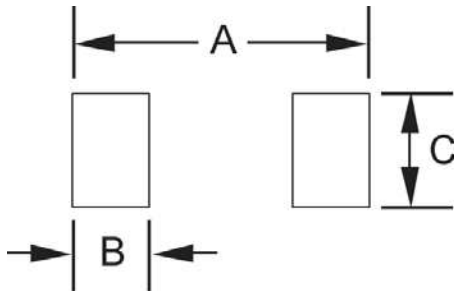


FIGURE 2
CAPACITANCE vs. ZENER VOLTAGE (TYPICAL)

PACKAGE DIMENSIONS


DIM	INCH		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.063	0.067	1.60	1.70
B	0.130	0.146	3.30	3.70
C	0.016	0.022	0.41	0.55

PAD LAYOUT


	inch	mm
A	.200	5.08
B	.055	1.40
C	.080	2.03